Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP X121 1G SFP LC SX Transceiver (J4858x)
HP X121 1G SFP LC LX Transceiver (J4859x)
HP X121 1G SFP LC LH Transceiver (J4860x)
HP X121 1G SFP RJ45 T Transceiver (J8177x)
HP X111 100M SFP LC FX Transceiver (J9054x)
HP X112 100M SFP LC BX-D Transceiver (J9099x)
HP X112 100M SFP LC BX-U Transceiver (J9100x)
HP X122 1G SFP LC BX-D Transceiver (J9142x)
HP X122 1G SFP LC BX-U Transceiver (J9143x)
HP X132 10G SFP+ LC SR Transceiver (J9150x)
HP X132 10G SFP+ LC LR Transceiver (J9151x)
HP X132 10G SFP+ LC LRM Transceiver (J9152x)
HP X132 10G SFP+ LC ER Transceiver (J9153x)
HP X171 1G SFP LC LH40 40km 1470nm CWDM Transceiver (J9677x)
HP X172 1G SFP LC LH80 80km 1470nm CWDM Transceiver (J9677x)
HP X171 1G SFP LC LH40 40km 1490nm CWDM Transceiver (J9678x)
HP X172 1G SFP LC LH80 80km 1490nm CWDM Transceiver (J9678x)
HP X171 1G SFP LC LH40 40km 1510nm CWDM Transceiver (J9679x)
HP X172 1G SFP LC LH80 80km 1510nm CWDM Transceiver (J9679x)
HP X171 1G SFP LC LH40 40km 1530nm CWDM Transceiver (J9680x)
HP X172 1G SFP LC LH80 80km 1530nm CWDM Transceiver (J9680x)
HP X171 1G SFP LC LH40 40km 1550nm CWDM Transceiver (J9681x)
HP X172 1G SFP LC LH80 80km 1550nm CWDM Transceiver (J9681x)
HP X171 1G SFP LC LH40 40km 1570nm CWDM Transceiver (J9682x)
HP X172 1G SFP LC LH80 80km 1570nm CWDM Transceiver (J9682x)
HP X171 1G SFP LC LH40 40km 1590nm CWDM Transceiver (J9683x)
HP X172 1G SFP LC LH80 80km 1590nm CWDM Transceiver (J9683x)
HP X171 1G SFP LC LH40 40km 1610nm CWDM Transceiver (J9684x)
HP X172 1G SFP LC LH80 80km 1610nm CWDM (J9684x)
x = Revision Letter, A, B, C, etc.

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

PSG instructions for this template are available at EL-MF877-01

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver, small flatblade, Phillips, Torx, or hex as needed	
Pliers, needle nose or similar	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

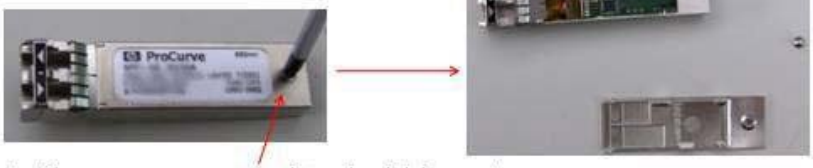
1. If the SFP transceiver has a sheet metal housing, it will be held in place with push tabs. Use a small, flatblade screwdriver to pry out the push tab.

2. With the latch bail pulled in line with the transceiver, pull the sheet metal housing from the backshell. Pliers may be useful in this step. If the housing is difficult to remove, a flatblade screwdriver can be use to pry part of it off, with pliers used to completely pull the housing off.
3. If the SFP transceiver has a completely die cast shell with a separate lid, remove the screws holding it in place with the appropriate screwdriver and remove the lid.
4. If the internal PCA is not fixed to the backshell, use a flatblade screwdriver to pry it out along with other mechanical components that may be used.
5. If the PCA is fixed to the backshell with a mounting screw, use the appropriate type of screwdriver to remove the screw, then follow the instructions in Step 4.
6. The SFP transceiver may have a separate, sheetmetal EMI shield close to the front. Use a small, flatblade screwdriver to pry it off.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

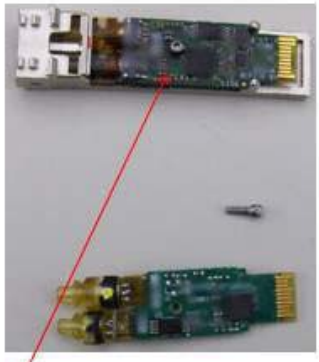
1. Pry out all retention tabs

2. Pull sheetmetal shell off



3. If screws are used to hold housing together, remove using correct screwdriver

4. Typical components



5. If present, remove screw holding PCA to housing

6. If necessary, remove EMI shield. Typical shield is shown here.